

Status of WP2 (On-detector power distribution)

F.Faccio, S.Michelis, G.Blanchot, C.Fuentes, B.Allongue - decrease in manpower as from Jan 1st with departure of S.Orlandi (fellow)

Outline

ASIC
Technology
Design
Full converter boards
Air-core inductor
Low-noise board design
Integration in detector systems

	AMIS2
Full control loop	\checkmark
Dead times' handling	Fixed
On-chip regulator	No
Soft Start	Simple RC
Over-I protection	No
Over-T protection	No
Under-V disable	No

	AMIS2	IHP1
Full control loop	\checkmark	\checkmark
Dead times' handling	Fixed	Adaptive (QSW)
On-chip regulator	No	No
Soft Start	Simple RC	Simple RC with comparators
Over-I protection	No	No
Over-T protection	No	No
Under-V disable	No	No

	AMIS2	IHP1	IHP2	
Full control loop	\checkmark	\checkmark	\checkmark	
Dead times' handling	Fixed	Adaptive (QSW)	Adaptive (QSW and CCM, sharp	
On-chip regulator	No	No	\checkmark	
Soft Start	Simple RC	Simple RC with comparators	Full sequence with comparators	
Over-I protection	No	No	\checkmark	
Over-T protection	No	No	No	
Under-V disable	No	No	No	

	AMIS2	IHP1	IHP2	AMIS3
Full control loop	\checkmark	\checkmark	\checkmark	\checkmark
Dead times' handling	Fixed	Adaptive (QSW)	Adaptive (QSW and CCM, sharp	Fixed
On-chip regulator	No	No	\checkmark	\checkmark
Soft Start	Simple RC	Simple RC with comparators	Full sequence with comparators	Simple RC
Over-I protection	No	No	\checkmark	No
Over-T protection	No	No	No	No
Under-V disable	No	No	No	No

	AMIS2	IHP1	IHP2	AMIS3	AMIS4
Full control loop	\checkmark	\checkmark	\checkmark	\checkmark	\checkmark
Dead times' handling	Fixed	Adaptive (QSW)	Adaptive (QSW and CCM, sharp	Fixed	Adaptive (QSW and CCM, smooth
On-chip regulator	No	No	\checkmark	\checkmark	\checkmark
Soft Start	Simple RC	Simple RC with comparators	Full sequence with comparators	Simple RC	State machine
Over-I protection	No	No	\checkmark	No	\checkmark
Over-T protection	No	No	No	No	\checkmark
Under-V disable	No	No	No	No	\checkmark



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- Packaged in QFN32 for system testing (as AMIS2)





- Internal BGP ref (as AMIS2) and Linear Voltage Regulators to provide on-chip 3.3V from unique input rail
- Integrated feedback loop with bandwidth of 100Khz can be lowered with external passives
- Internal oscillator fixed at 2MHz, tunable with external components
- Vout set to 2.5V, tunable with external components
- Protection features:
 - SEU-protected state machine rules entrance and exit from failure states and beginning of Soft Start (about 2ms long)
 - Under-voltage detection at the input enables converter only above 5V
 - Over-T detection turns off the converter when on-chip T exceeds 100C
 - Over-current detection is implemented on a cycle-by-cycle basis, and limits max current on HS transistor on each cycle. After 32 consecutive detections (synchronous with clock), the converter is reset and a Soft Start begins
- Other features:
 - Enable pin to turn on-off the converter
 - * Power good output flag (only asserted during 'good' state of the converter, with regulated Vout)
- Chip Size: ~2.875 x 2.55 mm2
- Packaged in QFN-EP 32 (first lot in QFN48 for functional test)
- To reduce parasitic resistance, unusual bonding configuration chosen (pads in the middle of the chip). Discussions ongoing via IMEC with packaging house (ASE) to find appropriate, cheap and reliable assembly
- Submitted to IMEC MPW on January 24th. Purchase of 1 extra wafer should ensure availability of at least 100 parts (probably more)
- We expect testing in summer

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Wednesday, February 9, 2011

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 - It will be used to simulate the converter embedded in a detector system



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 Example: start-up at 1A load followed by step-increases of 2A. At 7A, overcurrent protection is active.



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 - Air core toroidal inductors not available commercially: custom development enabled for mass production is required
- Development succeeded with Coilcraft:
 - * 220nH/30mΩ air core toroid
 - Coil mounted on plastic stand-off to fit precisely above the converter ASIC
 - Prototypes delivered in 2010. One sample successfully radiation tested at PS (8E15 p/cm²)
 - Order for production of 500 samples issued, delivery end of March
 - * Expected total mass: slightly less than 0.4g









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 - Addition of shield for segregation of noisy and quiet areas of PCB.













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 - Very compact design, need only for few external components





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- Using a commercial DCDC circuit (LTC3605) SM01C
 - Designed to provide up to 5A to match requirements of ATLAS SCT prototype modules







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• A stave module was powered with two SM01C converters and its performance was compared with the one obtained using a linear power supply (test done at Liverpool, then at CERN with UniGe module)



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- A residual magnetic field emitted from the DCDC board fitted with plastic coated shield raises the noise of the front-end
- When using a copper foil shield instead, the reference noise levels are recovered
- The compatibility between SM01C and the ATLAS stave modules is now achieved, using copper foil shields



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- Measurements with ATLAS SCT modules evidence the need for optimizing the shield
- 2 approaches have been followed to prototype manufacturable shields, both based on a coated plastic support. Metal (Cu) is either painted as a Cu-loaded varnish, or deposited (on-going work)
 - A dedicated test board has been developed to measure the effectiveness of all shields and define the optimum material and thickness
 - A simulation study will be performed and results compared to experimental benchmarks

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and work mainly



lunes 17 de enero de 2011



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- Phase2 upgrade of ATLAS TileCal (Argonne NatLab, Chicago, G.Drake)
- Phase1/2 upgrade of ATLAS LAr calorimeter (BNL, J.Kierstead)
- Phase2 upgrade of LHCb calorimeter (Barcelona, D.Gascon)

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Summary

- ASIC
 - Technology
 - * On-semi 0.35um technology fully validated. This is baseline for Phase1 developments
 - * IHP 0.25um technology still under evaluation, in collaboration with IHP. SEB test in April should tell if this technology is quickly usable for our development
 - Design
 - * 2 prototypes in production in On-Semi 0.35um. AMIS4 contains full protection features and is very close to a final design (to be confirmed by measurements...)
- Full converter boards
 - * Low-noise board design
 - * Know-how acquired and confirmed by results
 - Low-noise and compact prototypes available for both ASIC and commercial DCDC
 - * Special components
 - * Inductor design chosen, transferred to industry and in production
 - * Shield requirements being studied, and prototypes produced
 - Integration in detector systems
 - * Measurements on different systems confirm that power can be provided by DCDC converters without impacting the noise performance